

Physics of semiconductor detectors operation at low temperatures

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Outline

- 1. General on semiconductor detectors**
- 2. S/B and P-I-N detectors**
- 3. Radiation effect in detectors**
- 4. Diamond properties**
- 5. Trapping time degradation in Diamond and Silicon**
- 6. Signal amplitude in Diamond and Silicon detectors**
- 7. Conclusions**

Back ground of PTI group which has been used in this presentation

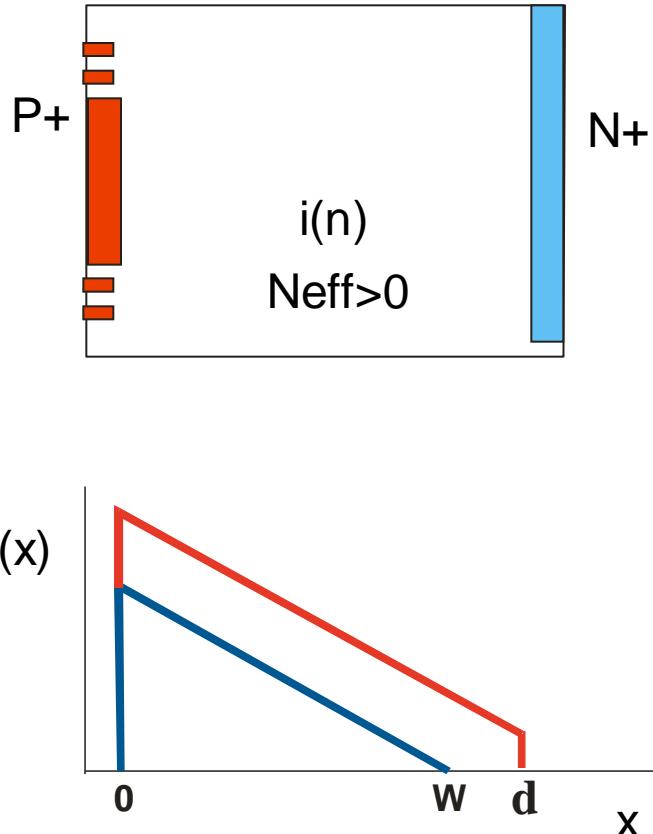
Performed R&Ds supported by international grants

1. CAST: R&D of **Transient Current Technique** for radiation hard detectors study (BNL).
2. ISTC: R&D of silicon **detectors array** for medical application (USA, for-profit company)
3. INTAS: R&D of radiation hard **cryogenic silicon detectors** (CERN-RD39 collaboration).
4. INTAS: R&D of silicon strip **detectors** for **ATLAS upgrade** (CERN-ATLAS).
5. INTAS: R&D of radiation hard **edgeless detectors** for **TOTEM** (CERN-TOTEM).
6. INTAS: R&D of spectrometric **DSSDs for EXL** (NuSTAR, FAIR).

Development and Fabrication of Si detectors in the frame of international projects

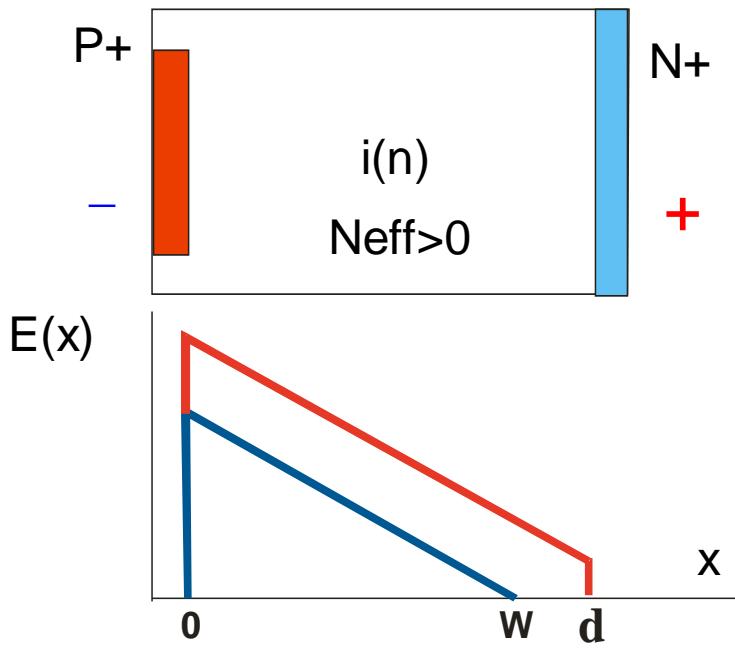
- **Current injected detectors** for CERN-RD39 collaboration.
- P-on-N detectors for “**TECHNOTECH**” project of CERN-RD50 collaboration
- Reference **P-on-N baby detectors** for CERN-ATLAS strip detectors QA.
- **Full set of edgeless detectors** for CERN-TOTEM experiment.
- **New** : pre-series run of **radiation hard silicon edgeless detectors** for CERN-TOTEM upgrade.
- **Si strip spectrometric detectors** for NuSTAR experiment in FAIR program (GSI)

Si planar detector, static

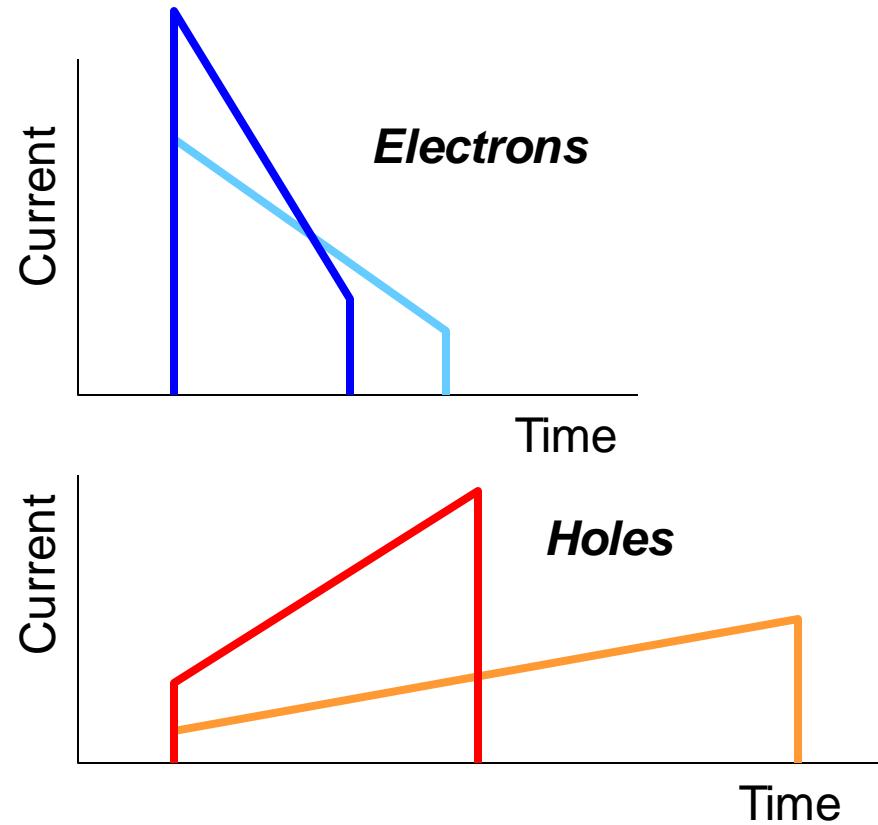


Electron mobility	... 1500cm²/v s
Hole mobility 450cm²/v s
V_{sat} 1 10⁷cm/s
d 300mkm
N_{eff} 1 10¹²cm⁻³
V_{fd} 30-100 V
V_{op} 100-300V
<E> 1 10⁴ v/cm

Si PAD detector response



$$J = 1/d \times q \mu E$$



Drift time ... 3 – 50 ns

TCT data (830 nm laser)

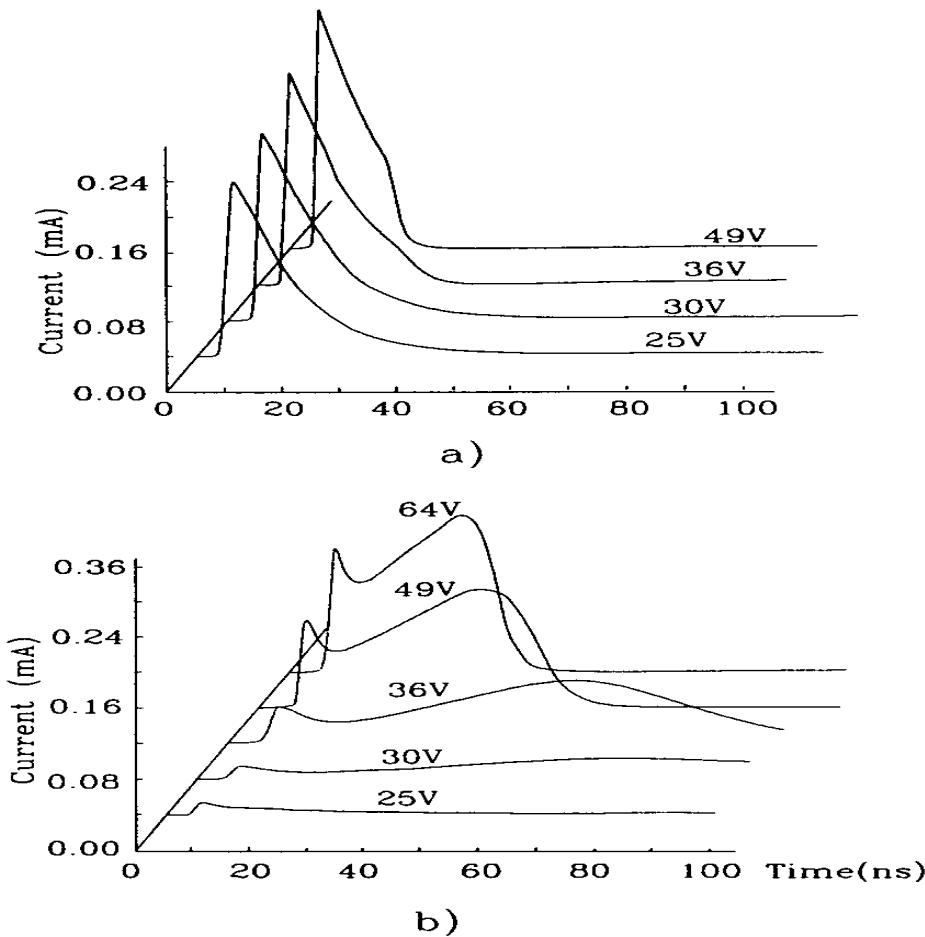
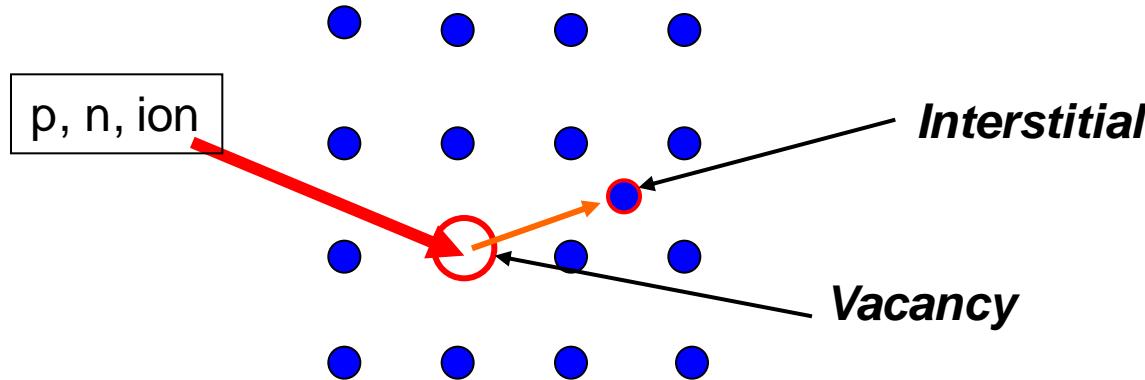


Fig. 9. A set of current pulses before and after depletion voltage for a deep level free detector: non-equilibrium carriers are generated (a) near the front p^+ -contact (drift of electrons); (b) near the back n^+ -contact (drift of holes).

Effect of irradiation on detector



Primary defects (Frenkel pairs): **vacancy (V)** and **interstitial (I)**

Secondary defects:

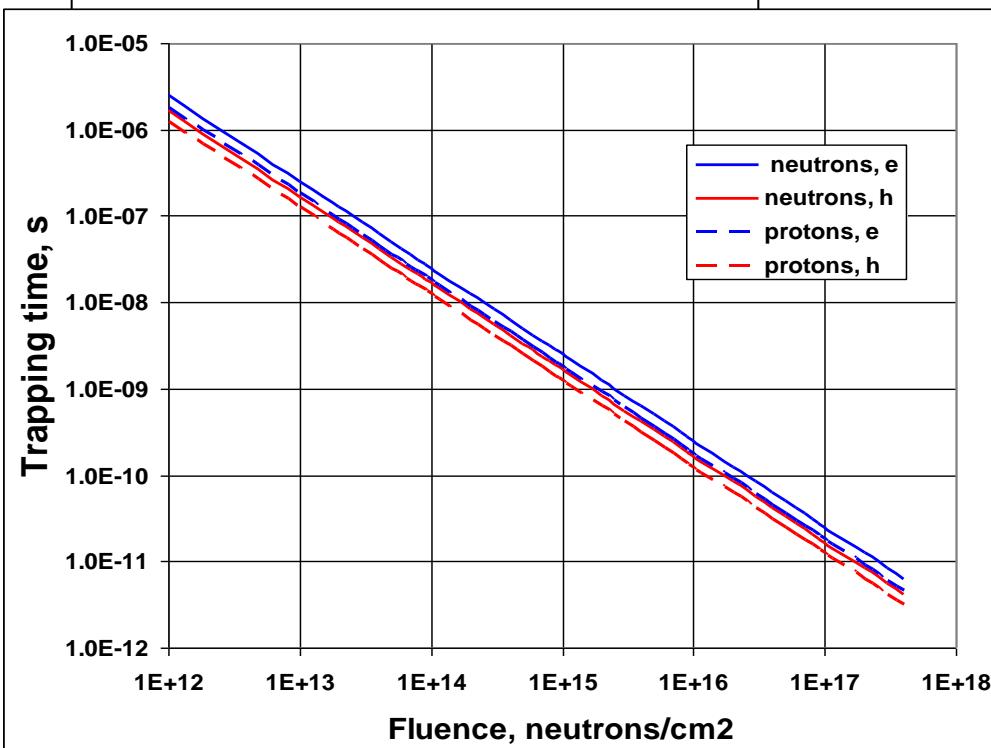
Divacancy $-V + V$

A center $-V + O$

E center $-V + P$

Life time degradation in Si

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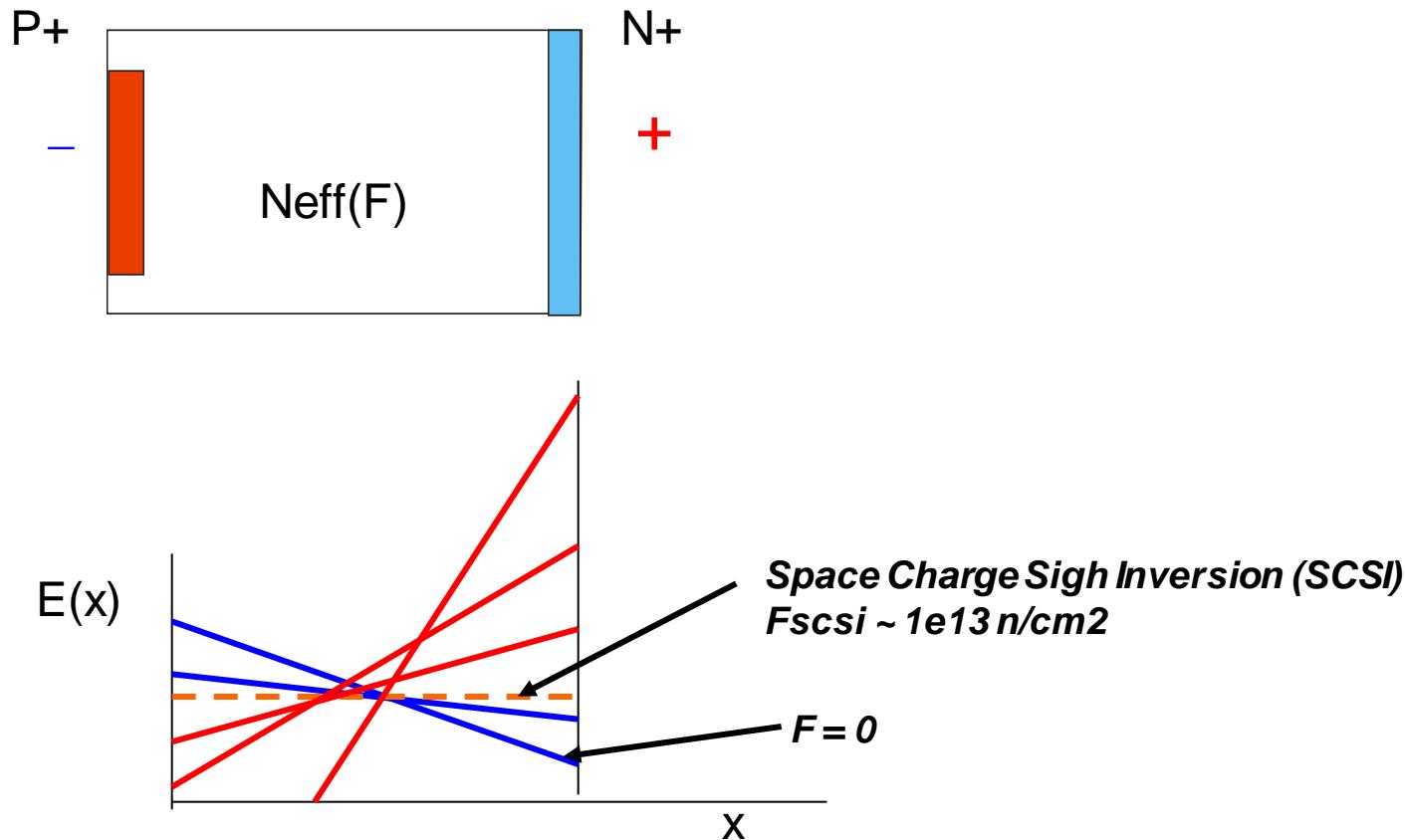


$$\tau(\phi) = (1 / \tau_0 + \beta\phi)^{-1}$$

Trapping probability (protons)

T_e^0	1×10^3
β_e	5.5×10^3
T_h^0	1×10^3
β_h	8×10^3

Electric field evolution in Si detectors with fluence (simple model)



Basic formulas

- Charge Collection Distance (CCD)

$$CCD = V_{dr} \times T_{tr}$$

- Trapping time

$$T_{tr} = (\sigma \times V_{th} \times N_{tr})^{-1}$$

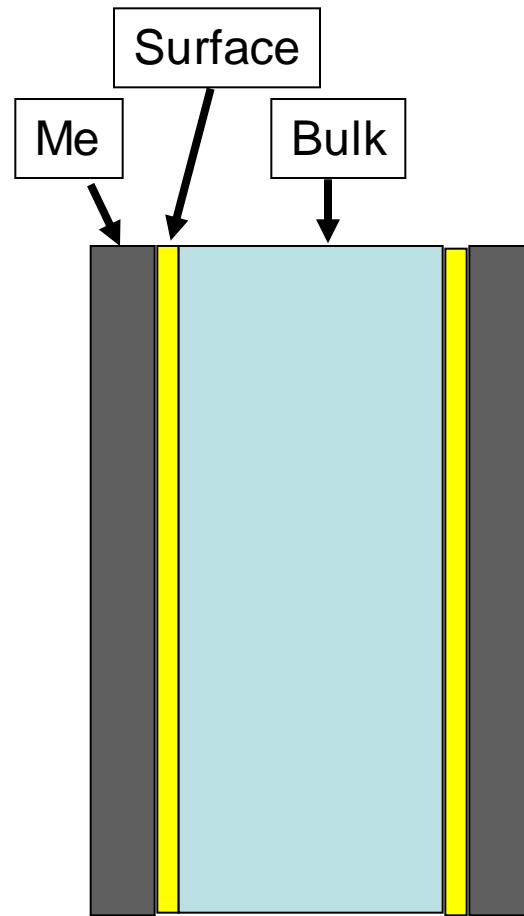
- Detrapping time

$$T_{dtr} = [(\sigma \times V_{th} \times N_c \times \exp(-E_{act}/kT)]^{-1}$$

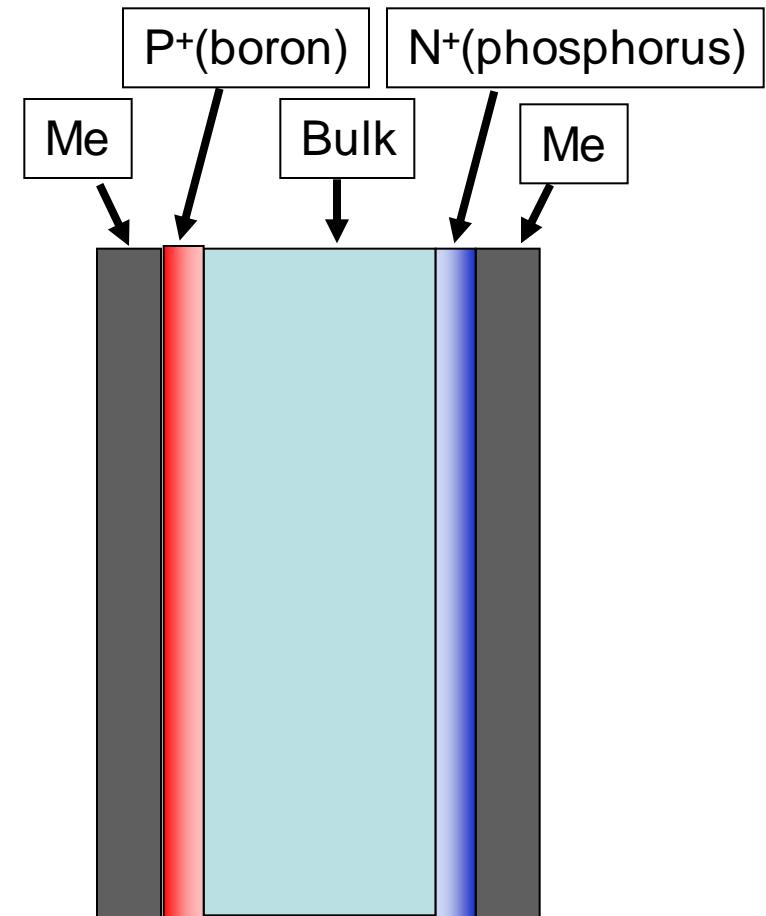
- Width of the depleted layer in P-N junction

$$W = \left(\frac{\epsilon \epsilon_o \cdot V}{2\pi q_e^2 N_{eff}} \right)^{\frac{1}{2}}$$

Comparison of Surface-barrier and P-I-N detectors

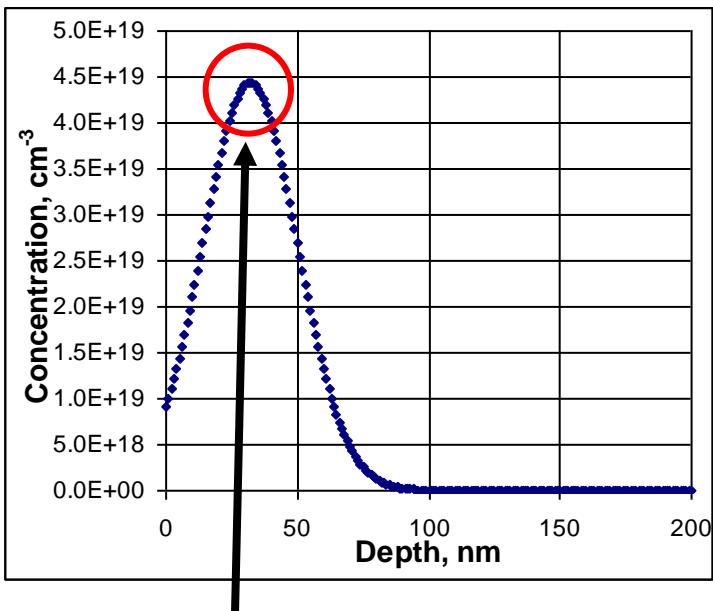


S/B detector
or M-S-M

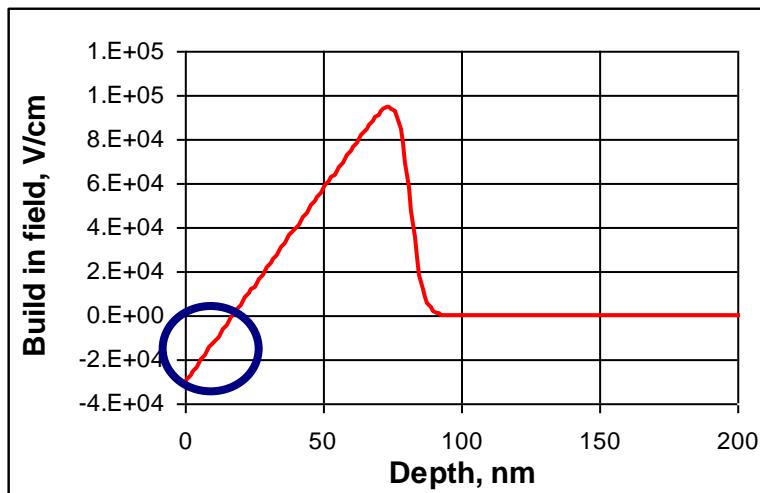
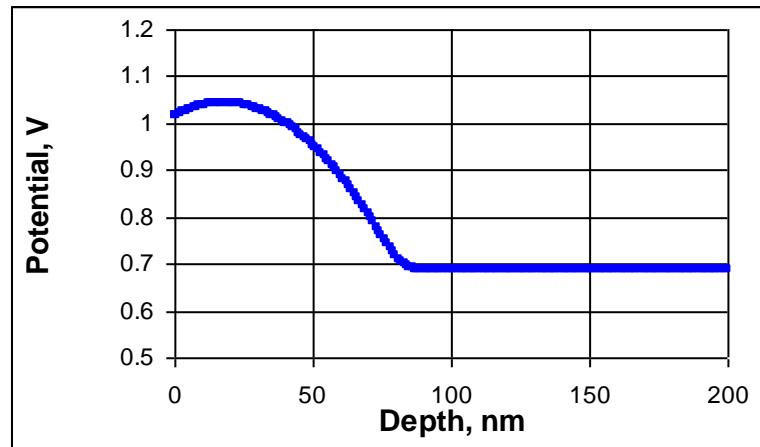


P-I-N

Electric field and potential at the detector entrance window



Degenerate Silicon
Si=Me



Comparison of S/B and P-I-N detectors

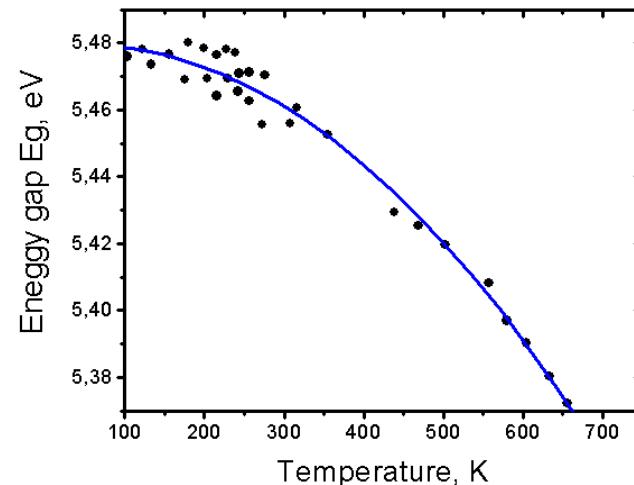
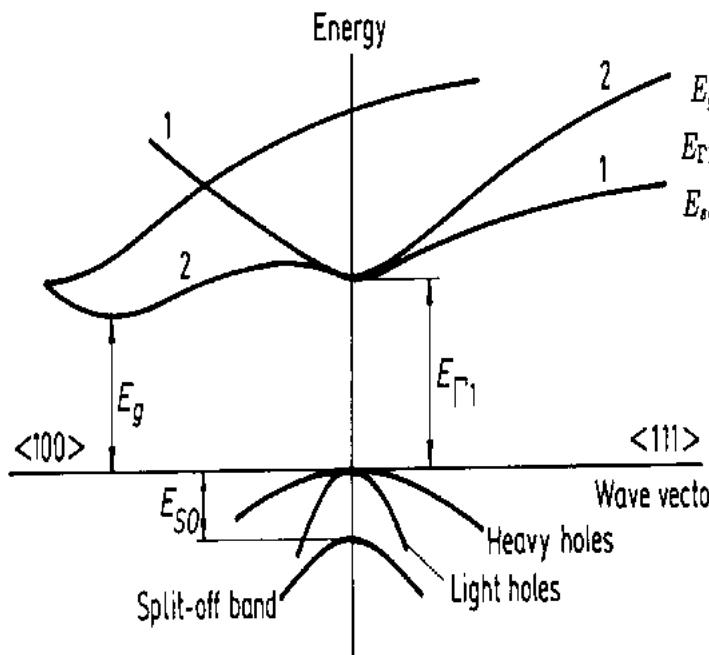
S/B

- Hardly controlled surface properties,
- Low reproducibility of S/B contact,
- Complicate technology,
- Oxidized surface or damaged interface prevents charge flow from the bulk to metal contact,
- High probability for charge accumulation at the interface and detector polarization,
- Unpredictable scenario of long term detector stability,
- Problem for operation at high current density,
- Optimal for low T operation in case the mentioned above problems will be solved.

P-I-N

- Reproducible technology,
- Smooth transition between bulk and me contact
- No interface between Si and Metal contact
- No chance accumulate charge at the surface
- No polarization,
- Requires more study for low T operation mainly for highly doped regions.

Band diagram for Diamond

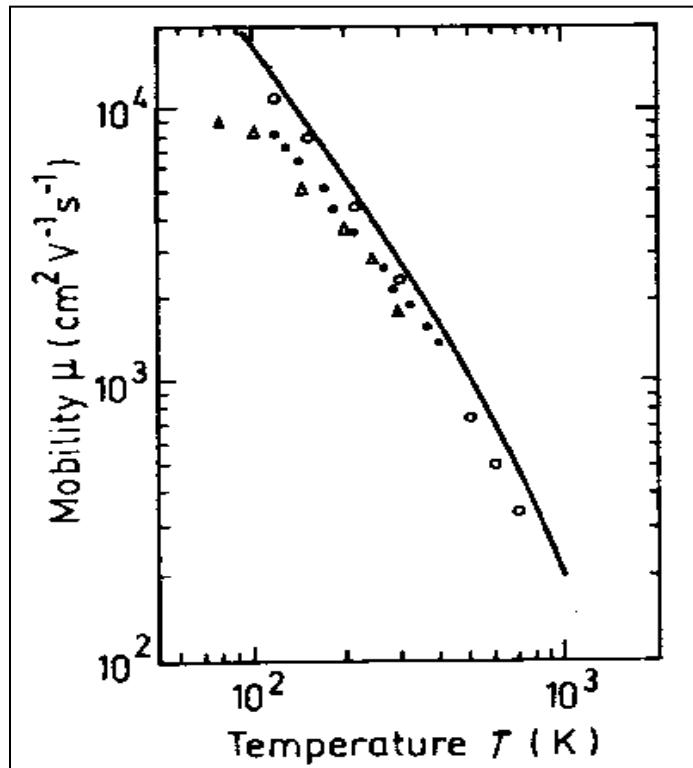


$N_c \sim 10^{20} \text{ cm}^{-2}$
 $N_v \sim 10^{19} \text{ cm}^{-2}$
 $N_i \sim 10^{-27} \text{ cm}^{-2}$

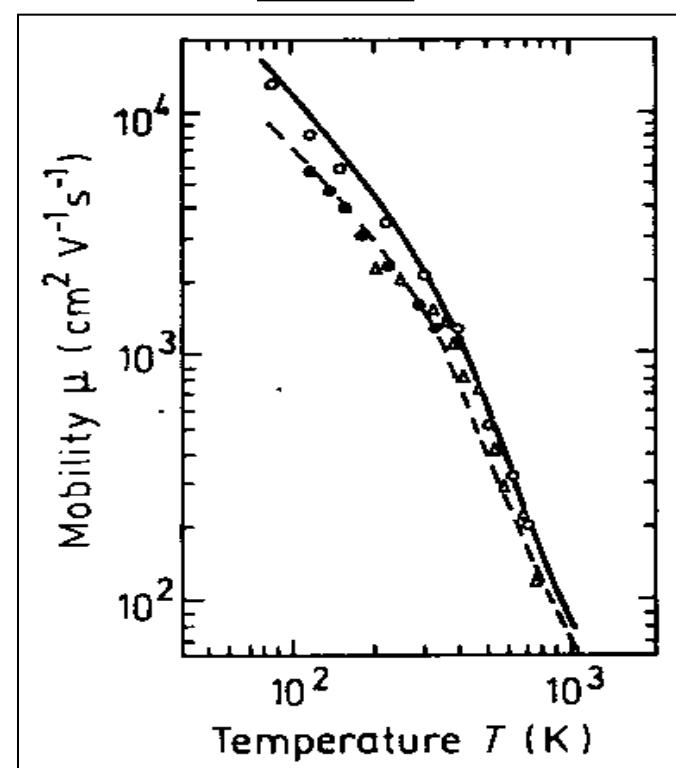
Band diagram depends in the crystal axes – anisotropy of parameters is expected

Mobility in natural diamond

electrons

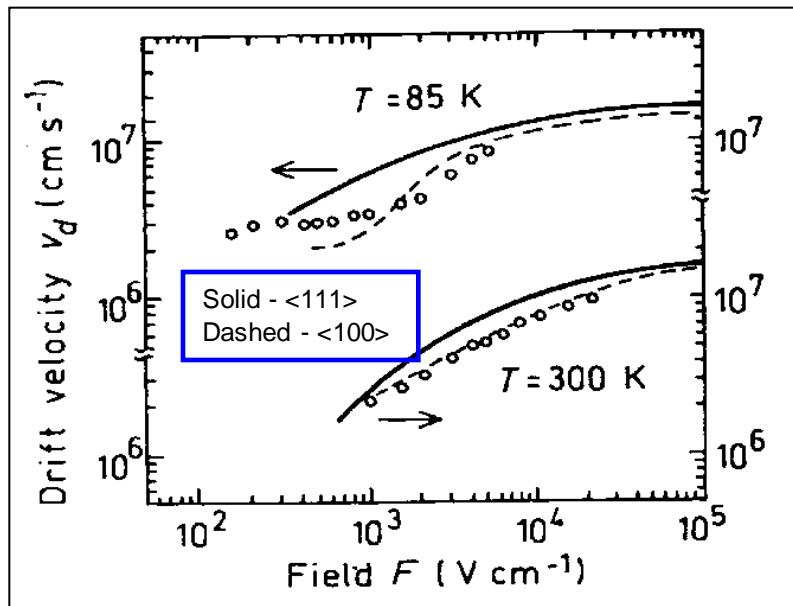


holes

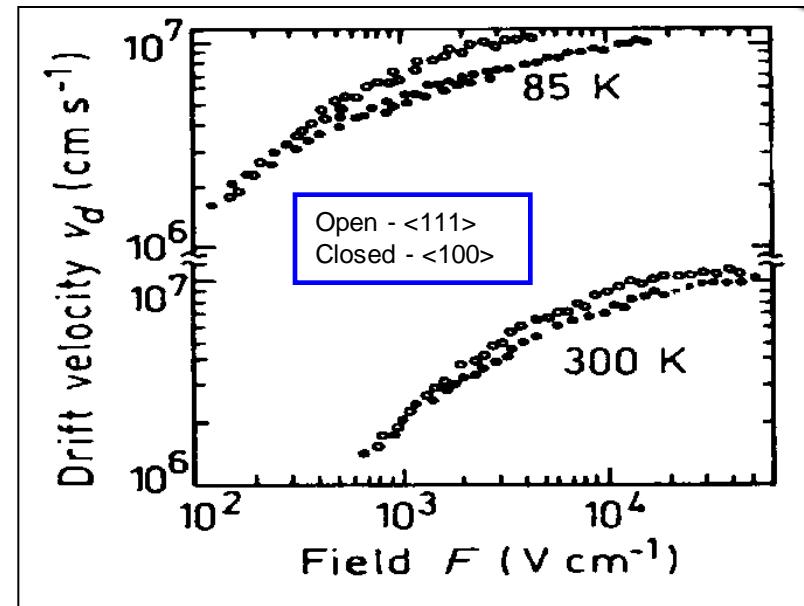


Anisotropy of drift velocity

electrons

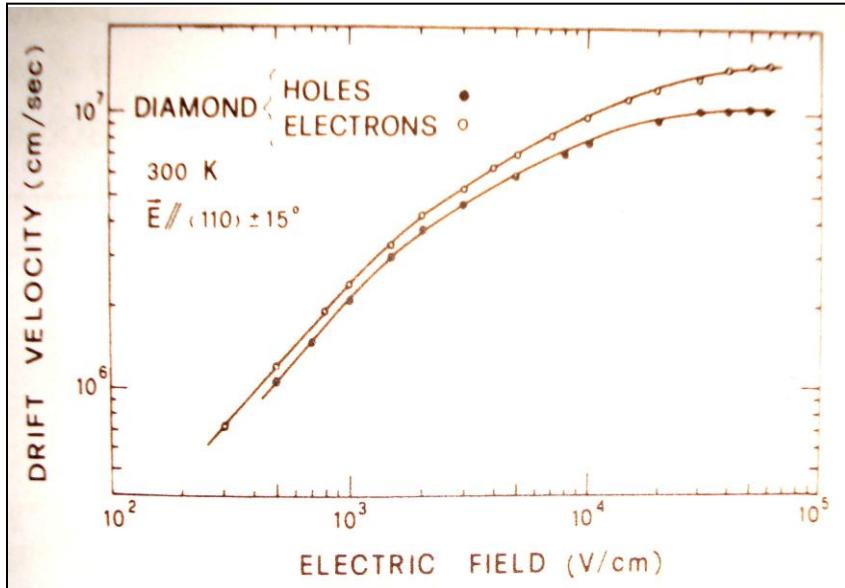


holes

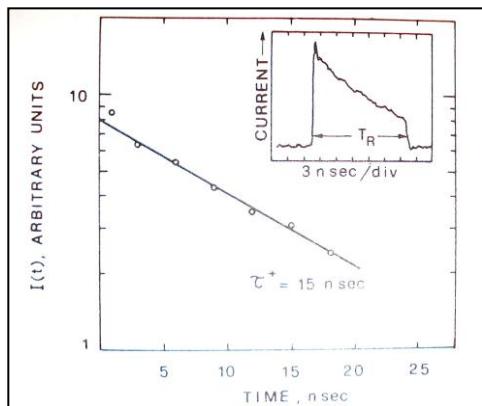
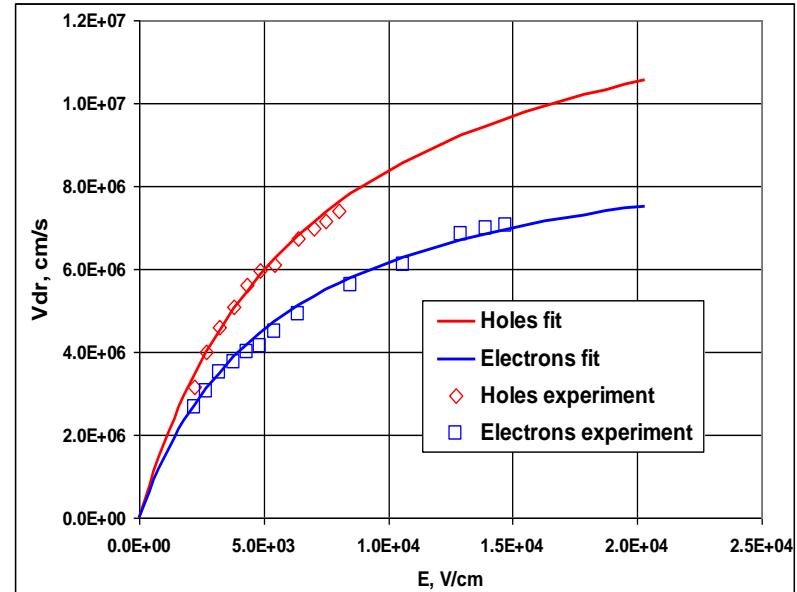


Drift velocity in modern Diamond

Natural



sc-CVD



	holes	electrons
μ_0 , cm/Vs	2100	2400
V_s , cm/s	1.05×10^7	1.50×10^7

	holes	electrons
μ_0 , cm/Vs	2064	1714
V_s , cm/s	1.41×10^7	9.60×10^6

From C.Canali,
NIM 160 (1979) p. 73-77

$$V_{dr} = \mu_0 E / (1 + \mu_0 E / V_s)$$

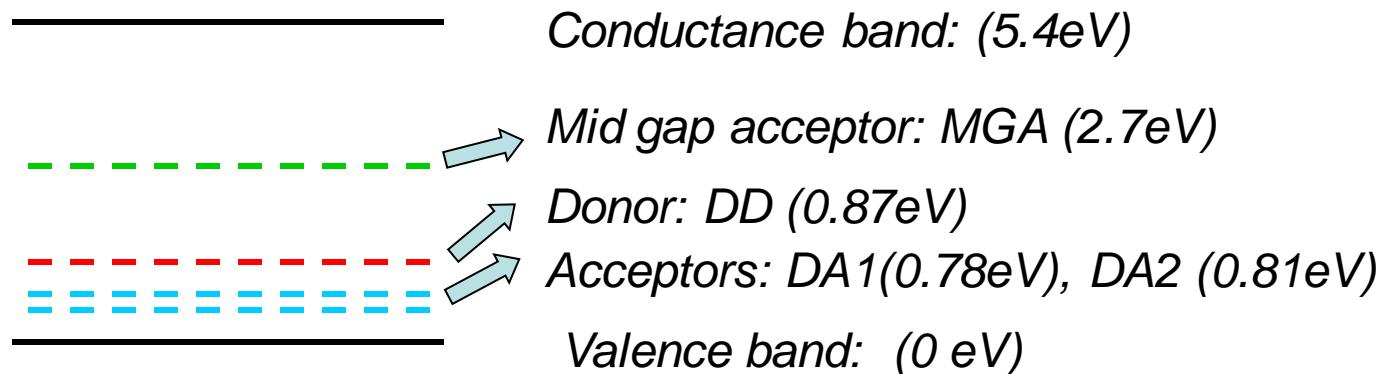
Effect of drift velocity anisotropy ???

Deep levels in CVD diamond

- INFN - Florence) model

Proofed by :thermal stimulated current measurements – TSC and PICTS

Photoconductivity measurements



What does this model define ??

Trends in the improvement of CVD diamond technology

DL's concentration

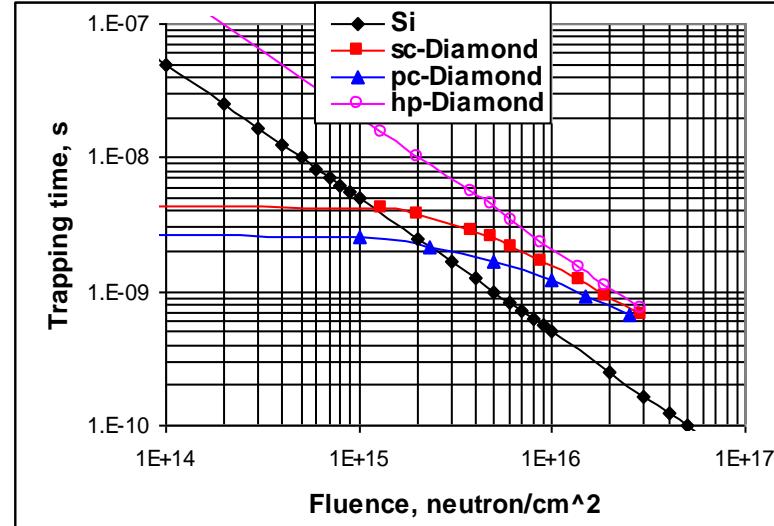
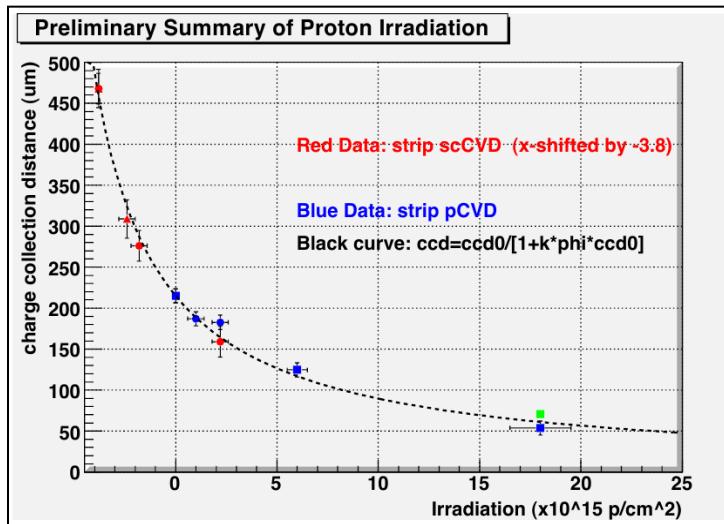
Years	1998	2000
MGA , cm ⁻³	5×10^{15}	2.5×10^{15}
DD , cm ⁻³	5×10^{15}	2.5×10^{15}
DA1 , cm ⁻³	3×10^{14}	4×10^{13}
DA2 , cm ⁻³	6×10^{13}	2×10^{13}

Bulk diamond parameters

E_f , eV	0.935	0.964
n , cm ⁻³	1.84×10^{57}	5.8×10^{57}
p , cm ⁻³	8.61×10^2	2.68×10^2
p , Ohm cm	4×10^{12}	1.27×10^{13}
+N_{tr} (e) , cm ⁻³	3.57×10^{14}	5.99×10^{13}
-N_{tr} (h) , cm ⁻³	3.58×10^{14}	5.99×10^{13}
N_{tr eff} , cm ⁻³	7.15×10^{14}	1.2×10^{14}

- *Diamond is a p-type semiconductor*
- *Purification leads to:*
 - ✓ Decrease of Fermi level
 - ✓ Increase of resistivity
 - ✓ Increase of trapping

Trapping in irradiated Si and Diamond



From:
 W.Trischuk & RD42,
 Resent advanxes in diamond detectors

Conclusion:
 Trapping time degradation rate:
 Silicon $\beta = 2e-7$ cm²/s
 Diamond $\beta = 7.5e-7$ cm²/s

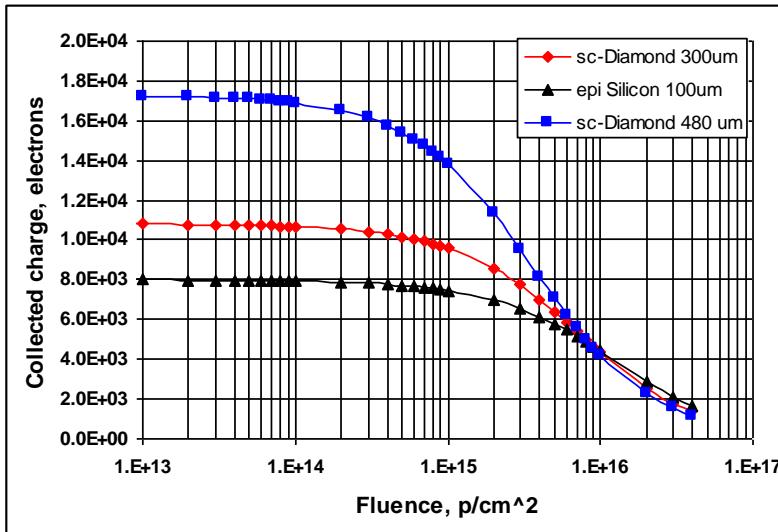
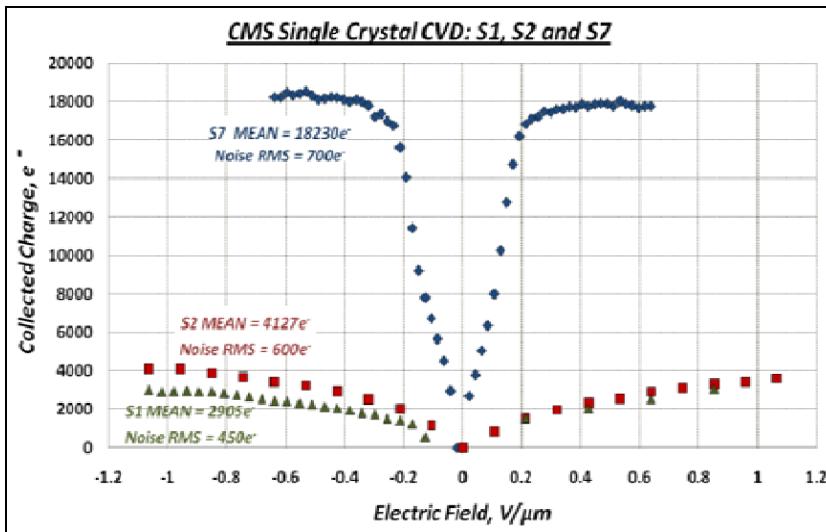
Conditions for comparison:
 Electric field 1V/um
 Diamond SC and PC
 Silicon MC
 Diamond irradiated by protons 24GeV
 Silicon irradiated by protons 24GeV

$$CCD = V_{dr} \cdot \tau$$

$$\tau \sim 1/N_{tr}$$

$$N_{tr} \sim F$$

Absolute signal in Si and Diamond PAD detectors (trapping time degradation effect)



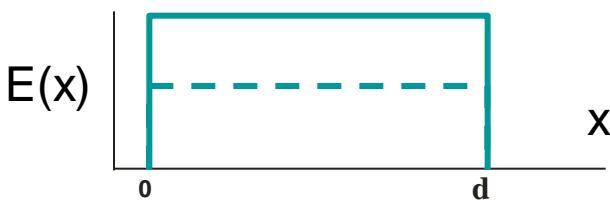
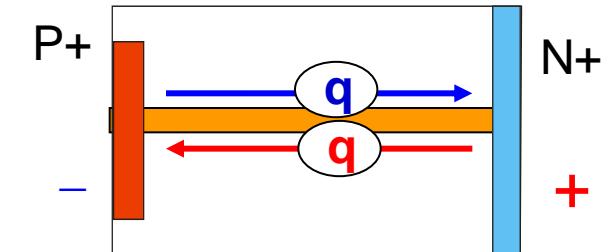
From “Fast beam conditions monitoring (BCM1F) for CMS” by
N/Bernardino Rodrigues, ...

$V_b = 300\text{V}$

sc-Diamond, 480um
at $F_p=1.75\text{e}15 \text{ 1/cm}^2$
 $Q_{coll} (\text{S1}) = 2900\text{e}$ and
 $Q_{coll} (\text{S2}) = 4130\text{e} !!!$
Expected > 10000e

Parameters
Uniform electric field
temperature - 290K
 $d(1/\tau)/dF$ silicon - $2\text{e}-7[\text{s}^{-1}\text{*cm}^2]$
 $d(1/\tau)/dF$ diamond - $7.5\text{e}-8[\text{s}^{-1}\text{*cm}^2]$

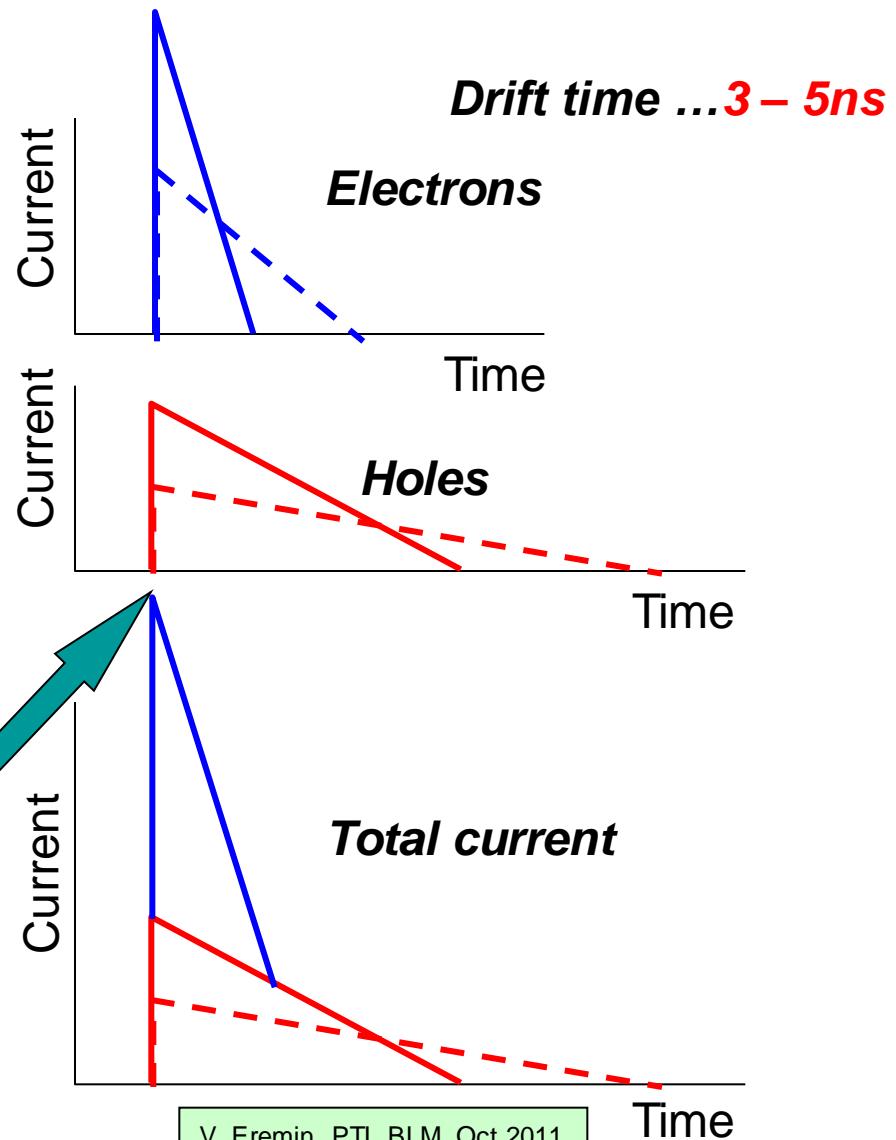
Current response of pad semiconductor detector (MIPs)



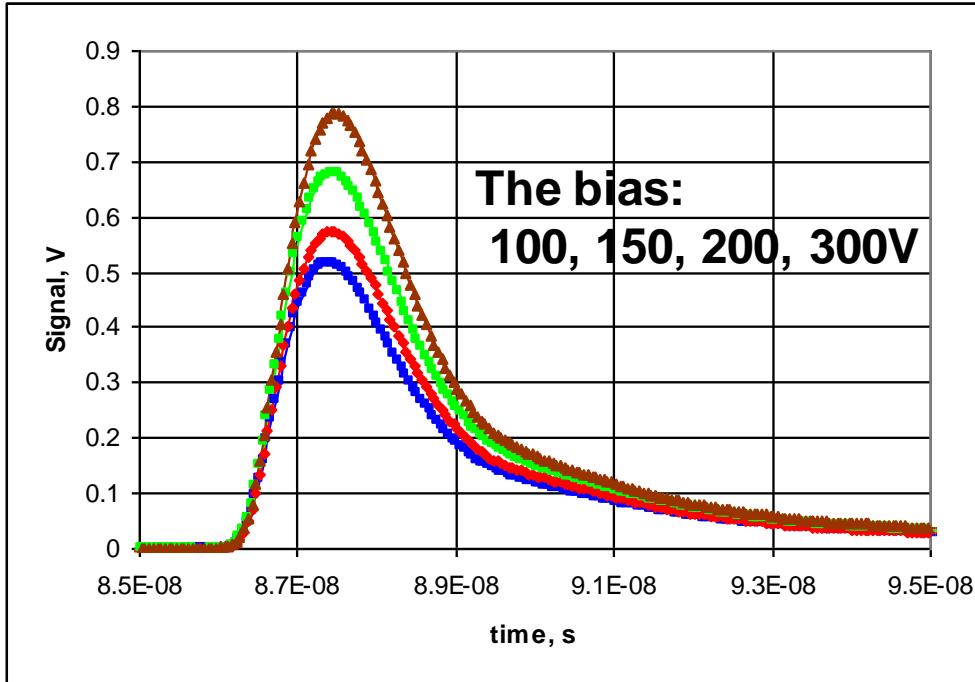
$d \dots\dots 300\text{mkm}$
 $N_{\text{eff}} \dots\dots 10^{11}\text{cm}^{-3}$
 $V_{fd} \dots\dots <20\text{ V}$
 $V_{op} \dots\dots 100-300\text{V}$

$$J_{\max} = 1/d q(Gd\mu_e E + Gd\mu_h E) = qG(\mu_e E + \mu_h E) = qG(v_e + v_h)$$

G – pair generation rate, 1/cm



MIP current response for Si detector



Detector thickness - 300 um
MIP detection (Laser 1060 nm)
Rise time - 600 ps (defined by electronics)
Expected time resolution <100 pc

Si and Diamond

Parameter	Silicon	pc-Diamond	sc-Diamond
Z	14	6	6
A	28.1	12	12
Density	2.329	3.515	3.515
Bend width, eV	1.12	5.48	5.48
Pair creation energy, eV	3.63	13.1	13.1
Permittivity	11.9	5.7	5.7
Resistivity, kOhm cm	<100	>1e10	>1e10
Drift mobility, cm^2/V/s	h	505	1000
	e	1450	1800
Saturation velocity, cm/s	h	8.4e6	1e7 ?
	e	1e7	2e7 ?
MIP pair generation density, cm-1	0.9e6	0.36e6	
MIP response amplitude, A	1.5e-6	1e-6	
Life/trapping time, ns	1e7	1 – 10	40
Charge collection distance, um	100000	< 200	> 500

Conclusions

1. Many physical parameters for Diamond are still not precisely defined: V_{dr}, mobility, V_s, trapping related parameters.
2. Shallow level impurities are not discovered for Diamond that makes impossible fabricate P-i-N structures.
3. Trapping time degradation is much less than for Silicon however the high density of defects and impurities limits the trapping time at the level equivalent of of flence $>1\text{e}15 \text{ p/cm}^2$
4. Polarization could be a major unpredictable factor of Diamond detector operation in DC current mode at low temperatures.

Thank you for your attention